



www.centralsemi.com

DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMXD6001 type contains three (3) Isolated Silicon Switching Diodes, manufactured by the epitaxial planar process, epoxy molded in a SUPERmini[™] surface mount package, and designed for switching applications requiring extremely low leakage.

MARKING CODE: X01

MAXIMUM RATINGS: (T _A =25°C) Continuous Reverse Voltage	SYMBOL VR	75	UNITS V
Peak Repetitive Reverse Voltage	V _{RRM}	100	V
Continuous Forward Current	١ _F	250	mA
Peak Repetitive Forward Current	IFRM	250	mA
Peak Forward Surge Current, tp=1.0µs	IFSM	4.0	А
Peak Forward Surge Current, tp=1.0s	IFSM	1.0	А
Power Dissipation	PD	350	mW
Operating and Storage Junction Temperature	т _Ј , т _{stg}	-65 to +150	°C
Thermal Resistance	Θ_{JA}	357	°C/W

ELECTRICAL CHARACTERISTICS PER DIODE: (T_A=25°C unless otherwise noted)

SYMBOL I _R	TEST CONDITIONS V _R =75V	Ω MIN	MAX 500	UNITS pA
BVR	I _R =100μΑ	100		V
VF	I _F =1.0mA		0.85	V
VF	I _F =10mA		0.95	V
VF	I _F =100mA		1.1	V
с _т	V _R =0, f=1.0MHz		2.0	pF
t _{rr}	I _R =I _F =10mA, I _{rr} =1.0mA, R _L =100Ω	!	3.0	μs

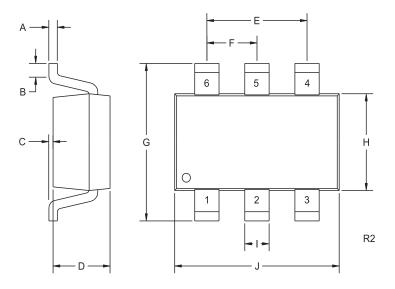
R4 (9-May 2011)



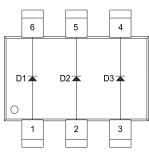
CMXD6001

SURFACE MOUNT TRIPLE ISOLATED ULTRA LOW LEAKAGE SILICON SWITCHING DIODES

SOT-26 CASE - MECHANICAL OUTLINE



PIN CONFIGURATION



DIMENSIONS						
	INCHES		MILLIMETERS			
SYMBOL	MIN	MAX	MIN	MAX		
А	0.004	0.007	0.11	0.19		
В	0.016	-	0.40	-		
С	-	0.004	-	0.10		
D	0.039	0.047	1.00	1.20		
E	0.074	0.075	1.88	1.92		
F	0.037	0.038	0.93	0.97		
G	0.102	0.118	2.60	3.00		
Н	0.059	0.067	1.50	1.70		
	0.016		0.41			
J	0.110	0.118	2.80	3.00		
SOT-26 (REV: R2)						

LEAD CODE:

- 1) Anode D1 2) Anode D2 3) Anode D3 4) Cathode D3 5) Cathode D2
- 6) Cathode D2

MARKING CODE: X01

R4 (9-May 2011)

www.centralsemi.com

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options

- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

CONTACT US

Corporate Headquarters & Customer Support Team

Central Semiconductor Corp. 145 Adams Avenue Hauppauge, NY 11788 USA Main Tel: (631) 435-1110 Main Fax: (631) 435-1824 Support Team Fax: (631) 435-3388 www.centralsemi.com

Worldwide Field Representatives: www.centralsemi.com/wwreps

Worldwide Distributors: www.centralsemi.com/wwdistributors

For the latest version of Central Semiconductor's **LIMITATIONS AND DAMAGES DISCLAIMER**, which is part of Central's Standard Terms and Conditions of sale, visit: <u>www.centralsemi.com/terms</u>

www.centralsemi.com

